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SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD

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[There are no amendments to this patent.]

Claims

1. A semiconductor characterized by the fact that at least one electrode of a second semiconductor chip and a chip part is connected to electrode pads for connection formed on a first semiconductor chip surface by a solder so that they face each other and are packaged with a resin.

2. A manufacturing method of the semiconductor device of Claim 1 characterized by the fact that it consists of a process that forms solder bumps on the above-mentioned electrode pads of the first semiconductor chip by the connection of the above-mentioned solder as well as a process that connects the electrode pads of the above-mentioned second semiconductor chip and chip part by the remelting of said solder bumps.